

CLAIMS:

1. A dicing/die bonding adhesion tape comprising a substrate, a silicone adhesive layer on the substrate, and a bonding layer on the silicone adhesive layer, wherein  
5 the tack strength between the silicone adhesive layer and the bonding layer is 0.2 to 2.0 N/25 mm, and said bonding layer is formed of an bonding composition comprising (A) a polyimide resin, (B) an epoxy resin, and (C)  
10 an epoxy resin curing catalyst.
2. The adhesion tape of claim 1, wherein the substrate is an extensible film.
- 15 3. The adhesion tape of claim 2, wherein the extensible film is polyethylene or polypropylene.
4. The adhesion tape of claim 1, wherein the silicone adhesive comprises a platinum addition-curable or  
20 radiation-curable silicone adhesive material.
5. The adhesion tape of claim 1, wherein the polyimide resin (A) in the bonding composition has phenolic hydroxyl radicals on its polymer skeleton.  
25
6. The adhesion tape of claim 1, wherein the polyimide resin (A) in the bonding composition has a siloxane structure in its polymer skeleton.